

大连化物所因公出访事前公示表

出访人团组成员基本信息：			
姓名	部门	职务	
张华民	DNL17	研究员	
出访国家或地区	美国华盛顿	顺访国家或地区	
出访任务	参加“2014 世界技术支持会议及展会”		
出国预算	30000 元人民币		
经费来源	<input checked="" type="checkbox"/> 课题组 _____ <input type="checkbox"/> 研究所 _____ <input type="checkbox"/> 国外资助单位 _____ <input type="checkbox"/> 其他资助单位 _____		
开始日期	2014. 6. 14	结束日期	2014. 6. 20
往返路线	大连-北京-华盛顿-北京-大连		
主要日程安排	6 月 14 日乘坐 CA1606 从大连飞往北京； 6 月 14 日乘坐 CA817 从北京飞往华盛顿； 6 月 19 日乘坐 CA818 从华盛顿飞往北京（6 月 20 日到达北京）； 6 月 20 日乘坐 CA8908 从北京飞往大连。		
邀请单位介绍	2014 世界技术支持会议是世界上最大的多学科多领域会议。该会议拥有世界一流的技术活动，重点在纳米技术、生物技术、洁净能源技术等。随着科学技术从单纯的研究阶段进入到商业化成熟阶段，2014 世界技术支持会议为其提供共多的国际合作机会。		



March 24, 2014

Professor Huamin Zhang
Dalian Institute of Chemical Physics, CAS
No.457 Zhongshan Road
Dalian, Liaoning 116023
P.R. CHINA

Dear Prof. Huamin Zhang:

We are pleased to invite you to attend the TechConnect World 2014 Conference, Expo and National Innovation Summit, June 15-18, 2014, to be held at the Gaylord National Convention Center, in National Harbor, Maryland, U.S.A. The following title has been selected for presentation:

Abstract submission number: 444

Title: The research and development of key materials of vanadium flow battery

Authors: Huamin Zhang

The TechConnect World is the home of five world-class events combined to create an extraordinary week where innovation technology solutions are matched to real-world business challenges. Co-located at the TechConnect World are the Nanotech, Microtech, Biotech, Cleantech and TechConnect Summit events. The TechConnect World brings together over 5,000 business and technical professionals including leading researchers, buyers, entrepreneurs, corporate business developers, investors, service providers, commercialization/technology transfer officers, industry analysts and members of the media.

Hotel rooms have been reserved at negotiated conference rates. Early reservation is recommended owing to high room demand during the conference period. Housing information and instructions may be found at <http://www.techconnectworld.com/World2014/venue/>

We strongly encourage you to book your accommodations as soon as possible. The conference cannot provide travel assistance or scholarship. If you have not already done so, please register for the conference here: <http://www.techconnectworld.com/World2014/register.html>

For questions about any conference details, please contact Sarah Wenning at wenning@techconnect.org. Please monitor the conference web pages at <http://www.techconnectworld.com/World2014> for program updates and announcements.

Thank you for your participation in the TechConnect World 2014 and we look forward to meeting you in June.

Sincerely,

A handwritten signature in blue ink that reads 'Sarah Wenning'.

Sarah Wenning
VP, Operations
TechConnect World